



Technical Data Sheet

Topadd® SG-400

SG-400 is general type processing aids . It can replace traditional acrylic base processing aids with balance lubrication and fusion performance , especially recommend for high filler formula such as Pvc pipe , pvc wall panel ,pvc stone floor ,ceiling panel .

Product benefits

- Good fusion property
- Good surface gloss
- Cost reduction

Technical specifications

Specification	Unit	Test standard	SG-400
Appearance	--	--	White powder or fine granule
Bulk density	g/cm3	GB/T 1636-2008	≥0.40
Sieve residue (30mesh)	%	GB/T 2916	≤2.0
Volatile content	%	ASTM D5668	≤1.5

Product application

SG-400 is especially recommend for high filler formula such as Pvc pipe , pvc wall panel ,pvc stone floor ,ceiling panel . It can replace Acrylic base processing aids with lower cost performance.

Package

25kg plastic woven bag or 20kg paper bag with PE liner bag.

Storage considerations:

The product can be stored under appropriate conditions for two years. But please keep products store in a dry ventilated environment (temperature should not exceed 30°C, in low humidity). Inappropriate storage environment may cause agglomeration. Especially at high temperatures & high humidity, it is recommended not to stack more than 30 days long, it may increase agglomeration phenomenon. Agglomeration does not affect the quality ,but agglomeration material is smashed before using .

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